

Pin Configuration

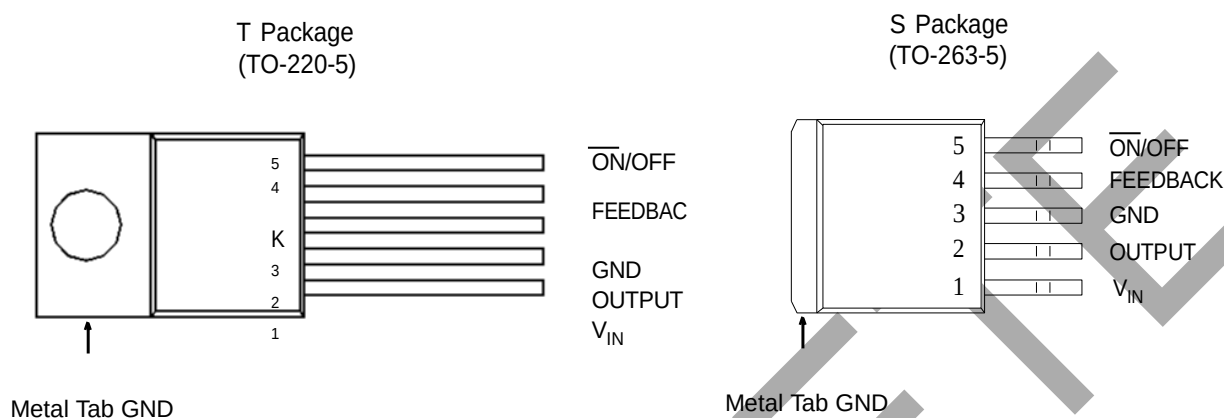


Figure 2. Pin Configuration of AP3003 (Top View)

Pin Description

Pin Number	Pin Name	Function
1	V_{IN}	Unregulated input voltage
2	OUTPUT	Switch driver output
3	GND	Ground
4	FEEDBACK	Feedback Pin. For fixed version, connect it to system output. For adjustable version, connect it with an external resistor and capacitor feedback network to program the system output voltage
5	ON/OFF	The TTL logic compatible input to control the regulator on or off

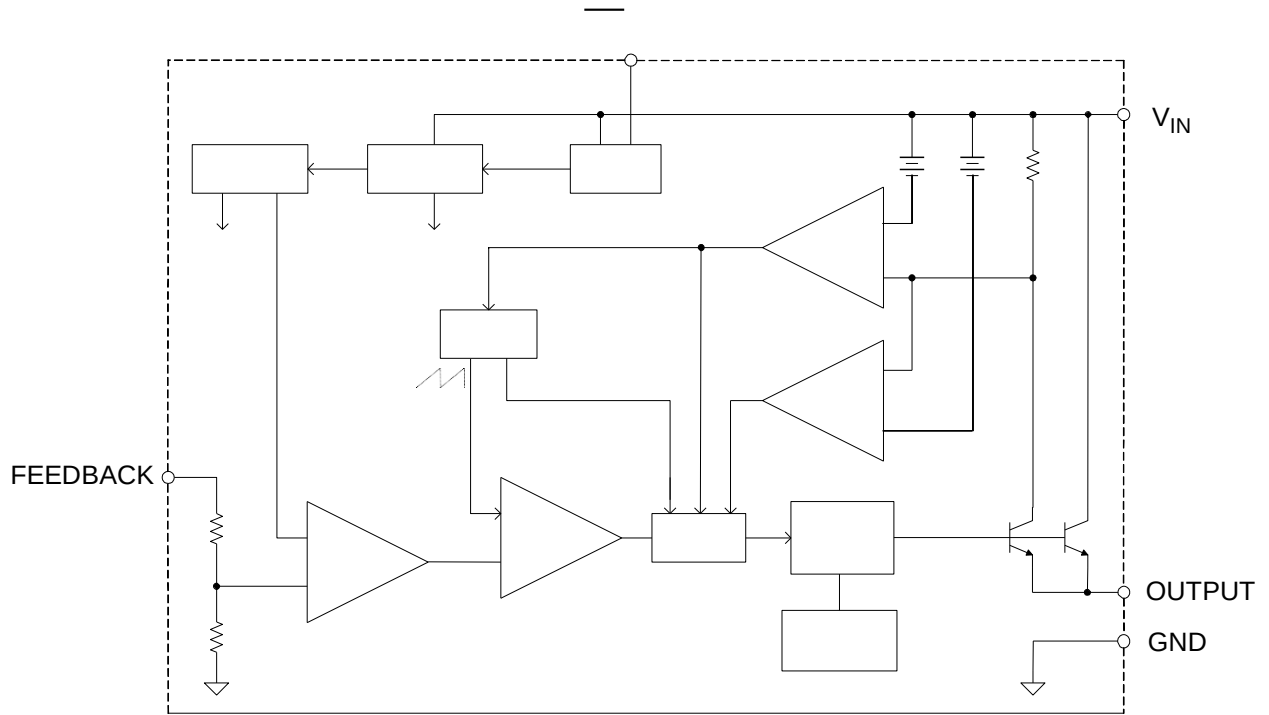
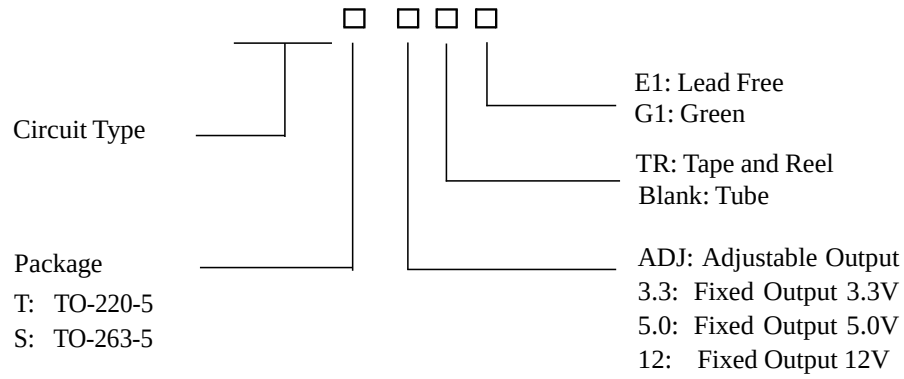


Figure 3. Functional Block Diagram of AP3003



Package	Temperature Range	Part Number		Marking ID		Packing Type
		Lead Free	Green	Lead Free	Green	
TO-220-5	-40 to 85°C	AP3003T-ADJE1	AP3003T-ADJG1	AP3003T-ADJE1	AP3003T-ADJG1	Tube
		AP3003T-3.3E1	AP3003T-3.3G1	AP3003T-3.3E1	AP3003T-3.3G1	Tube
		AP3003T-5.0E1	AP3003T-5.0G1	AP3003T-5.0E1	AP3003T-5.0G1	Tube
		AP3003T-12E1	AP3003T-12G1	AP3003T-12E1	AP3003T-12G1	Tube
TO-263-5	-40 to 85°C	AP3003S-ADJE1	AP3003S-ADJG1	AP3003S-ADJE1	AP3003S-ADJG1	Tube
		AP3003S-ADJTRE1	AP3003S-ADJTRG1	AP3003S-ADJE1	AP3003S-ADJG1	Tape & Reel
		AP3003S-3.3E1	AP3003S-3.3G1	AP3003S-3.3E1	AP3003S-3.3G1	Tube
		AP3003S-3.3TRE1	AP3003S-3.3TRG1	AP3003S-3.3E1	AP3003S-3.3G1	Tape & Reel
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input voltage		V_{IN}	40	V
ON/OFF Pin Voltage		$V_{ON/OFF}$	40	V
Feedback Pin Voltage		V_{FB}	40	V
Operating Junction Temperature		T_J	150	°C
Thermal Resistance (Junction to Ambient, No Heatsink)	TO-220-5	$R_{\theta JA}$	60	°C/W
	TO-263-5			
Lead Temperature (Soldering, 10sec)		T_{LEAD}	260	°C
Storage Temperature Range		T_{STG}	-65 to 150	°C

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Rec

Para				
Maxim				
	ADJ ($V_{OUT}=2.5V$)		25	
Operating Junction Temperature		T_J	-40 to 125	°C

Note 2: For ADJ version, the recommended supply voltage depends on the needed output voltage.



Temperature Range.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output Voltage	V_{OUT}	$5.5V \leq V_{IN} \leq 32V$, $0.2A \leq I_{LOAD} \leq 3A$	3.168 3.135	3.3	3.432 3.465	V
Efficiency	η	$V_{IN}=12V$, $I_{LOAD}=3A$		75		%

For 5V Output Voltage Version

Unless otherwise specified, $T_J=25^\circ C$. The specifications with **boldface type** apply over Full Operating Junction Temperature Range.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output Voltage	V_{OUT}	$7V \leq V_{IN} \leq 32V$, $0.2A \leq I_{LOAD} \leq 3A$	4.800 4.750	5	5.200 5.250	V
Efficiency	η	$V_{IN}=12V$, $I_{LOAD}=3A$		80		%

For 12V Output Voltage Version

Unless otherwise specified, $T_J=25^\circ C$. The specifications with **boldface type** apply over Full Operating Junction Temperature Range.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Output						
Efficiency						

For 2.5V Output Voltage Version

Unless otherwise specified, $T_J=25^\circ C$. The specifications with **boldface type** apply over Full Operating Junction Temperature Range.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Feedback Voltage	V_{FB}	$4.5V \leq V_{IN} \leq 25V$, $0.2A \leq I_{LOAD} \leq 3A$, V_{OUT} programmed for 2.5V	1.193 1.18	1.23	1.267 1.28	V
Efficiency	η	$V_{IN}=12V$, $I_{LOAD}=3A$, $V_{OUT}=2.5V$		73		%



$I_{LOAD}=500mA$, $T_J=25^{\circ}C$. Specifications with **boldface type** apply over Full Operating Junction Temperature Range.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Feedback Bias Current	I_{FB}	Adjustable Version Only, $V_{FB}=1.3V$		10	50 100	nA
Oscillator Frequency	f	(Note 3)	127 110	150	173 173	kHz
Saturation Voltage	V_{SAT}	$I_{LOAD}=3A$ (No output devices, $V_{FB}=0V$)		1.2	1.5 1.6	V
Maximum Duty Cycle	D_{MAX}	$V_{FB}=0V$		100		%
Minimum Duty Cycle	D_{MIN}	$V_{FB}=1.3V$		0		%
Current Limit	I_{CL}	Peak Current , No output devices, $V_{FB}=0V$	3.6 3.4	4.5	6.9 7.5	A
Output Leakage Current	I_{SWL}	Output=0V, No output devices, $V_{FB}=1.3V$, $V_{IN}=32V$		50		μA
		Output=-1V, No output devices, $V_{FB}=1.3V$, $V_{IN}=32V$		2	30	mA
Quiescent Current	I_Q	$V_{FB}=1.3V$		5	10	mA
Standby	-	—			200	
$\overline{ON}/CI$ Thresh						
$\overline{ON}/OI$						μA
						μA

Note 3:

Note 4:

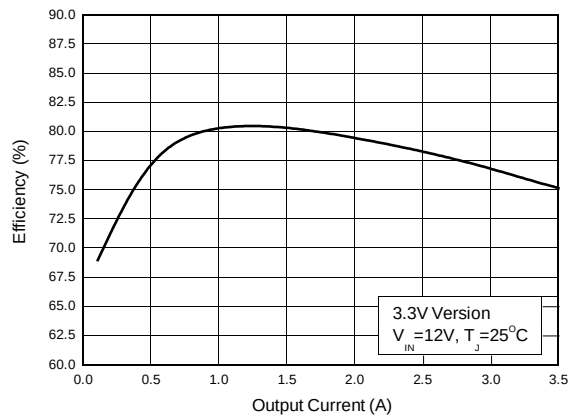


Figure 4. Efficiency vs. Output Current

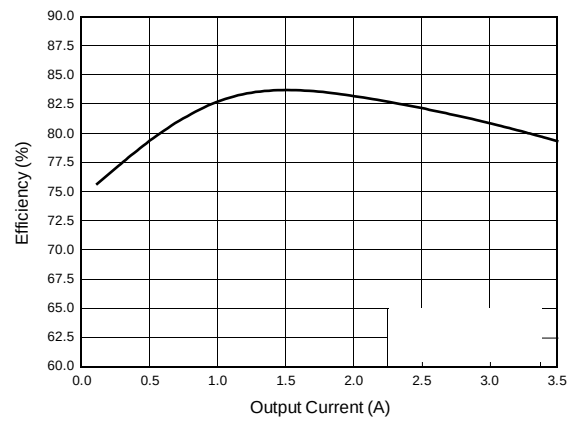


Figure 5. Efficiency vs. Output Current

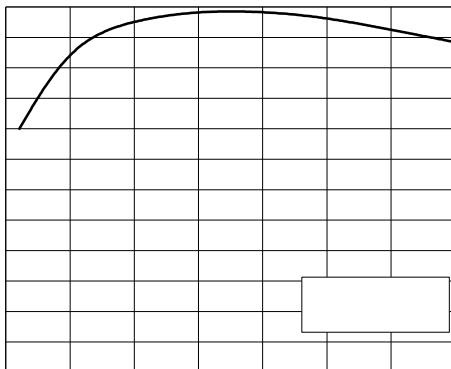


Figure 6. Efficiency vs. Output Current

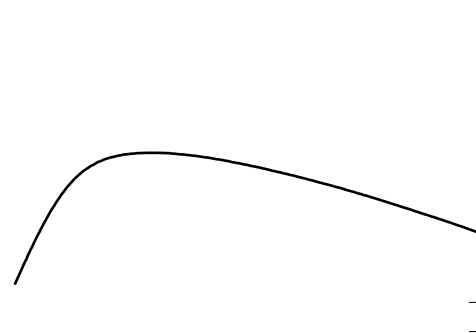


Figure 7. Efficiency vs. Output Current

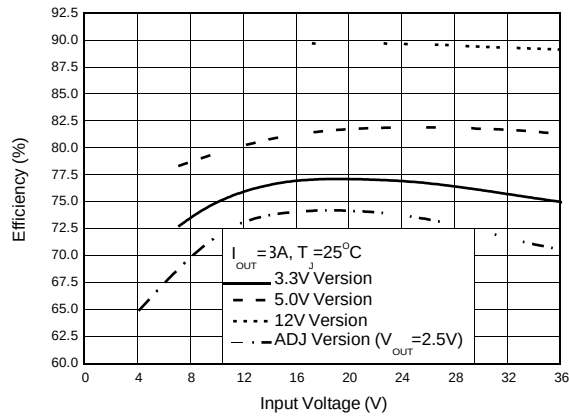
**150kHz 3A BUCK DC-DC CONVERTER****AP3003****Typical Performance Characteristics (Continued)**

Figure 8. Efficiency vs. Input Voltage

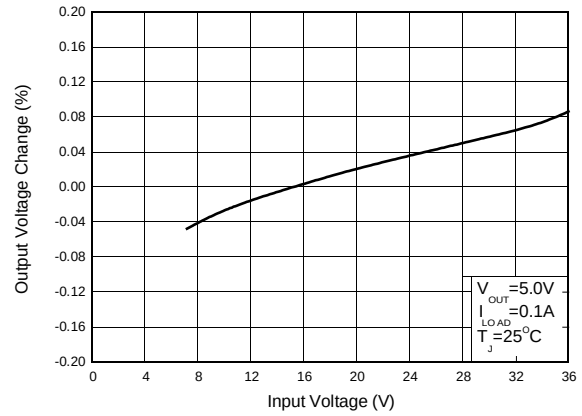


Figure 9. Line Regulation

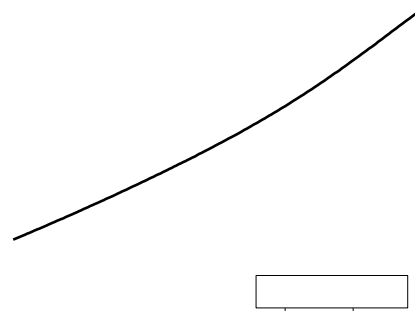


Figure 10. Load Regulation

Figure 11. Switch Saturation Voltage vs. Switch Current

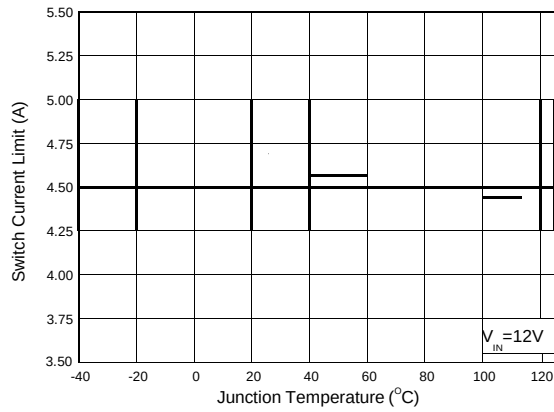
**150kHz 3A BUCK DC-DC CONVERTER****AP3003****Typical Performance Characteristics (Continued)**

Figure 12. Switch Current Limit vs. Junction Temperature

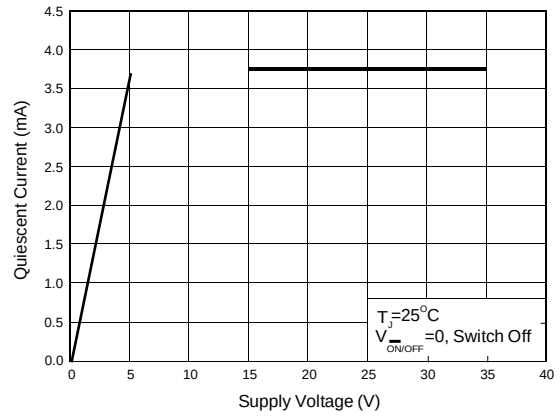


Figure 13. Quiescent Current vs. Supply Voltage

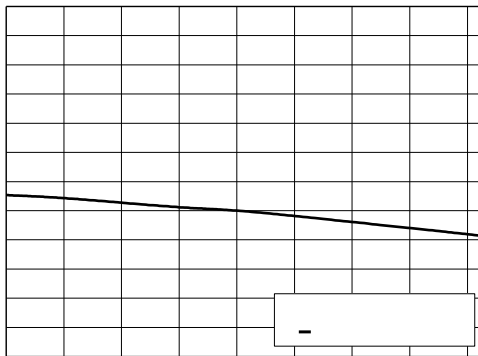


Figure 14. Quiescent Current vs. Junction Temperature

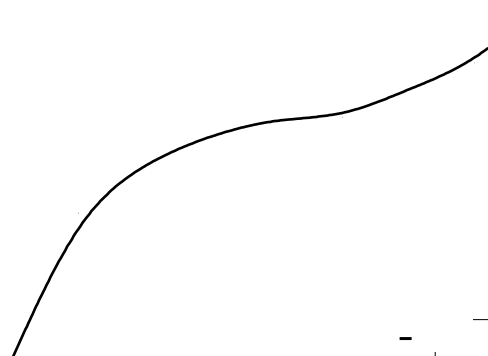


Figure 15. Shutdown Quiescent Current vs. Input Voltage

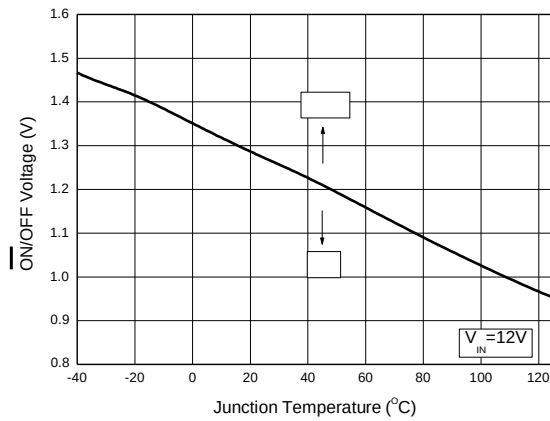


Figure 16. On/Off Threshold Voltage vs. Junction Temperature

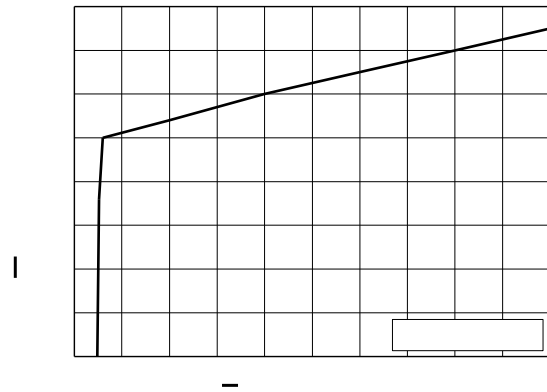
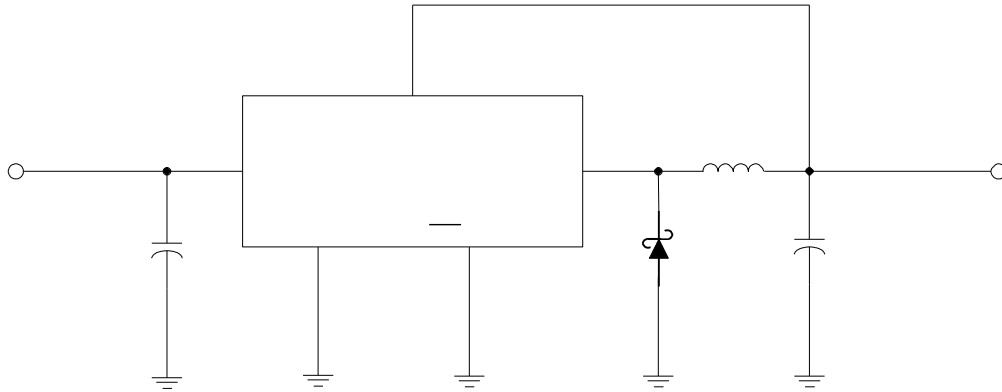


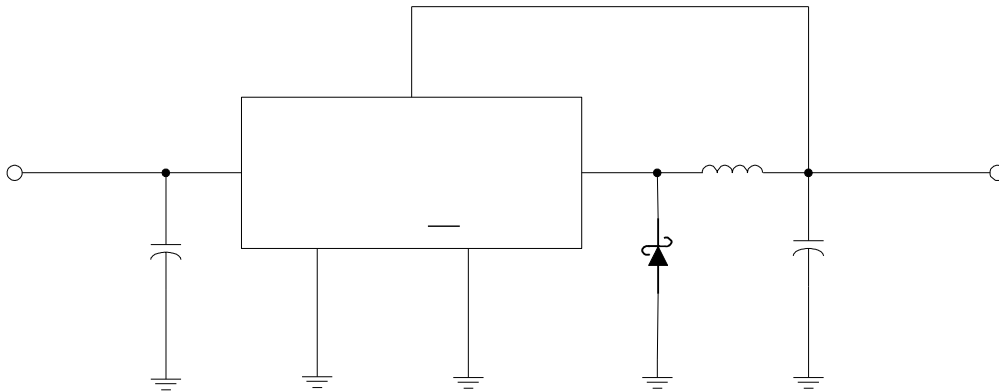
Figure 17. On/Off Pin Current vs. On/Off Pin Voltage

Figure 18. Switching Frequency vs. Junction Temperature



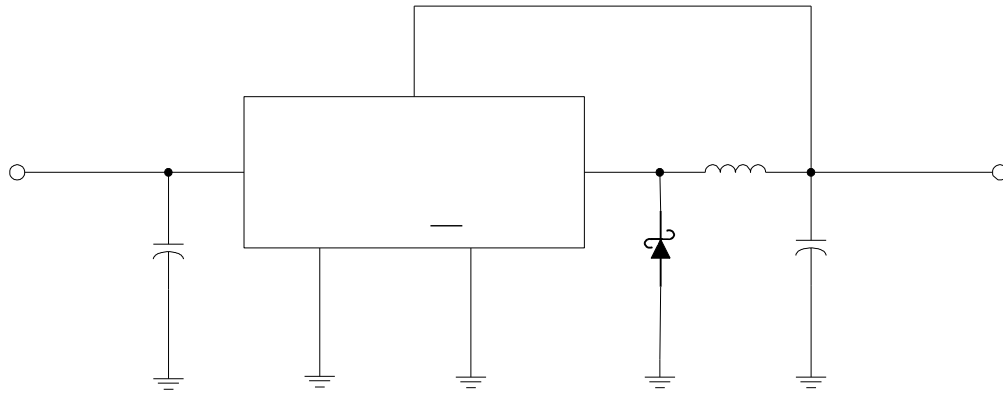
L1: Sumida CDRH127/LDNP-220MC or Equivalent

Figure 19. Typical Application of AP3003-3.3V



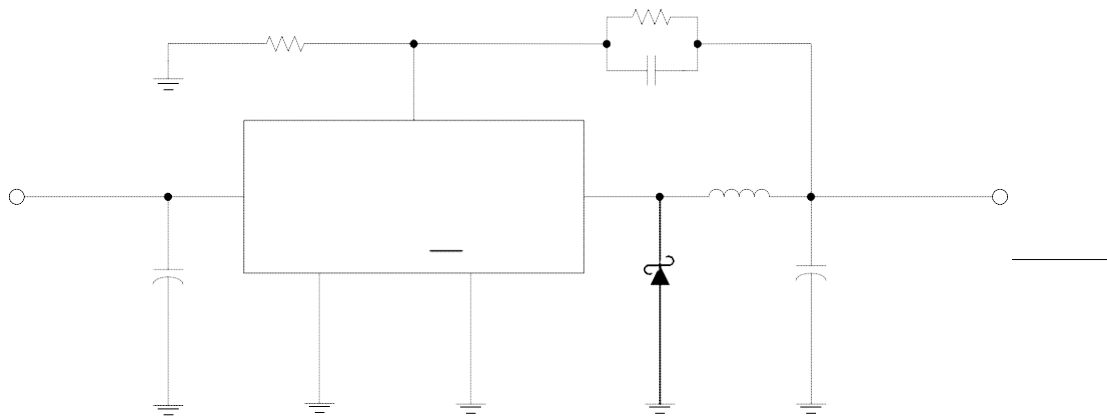
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Figure 20. Typical Application of AP3003-5.0V



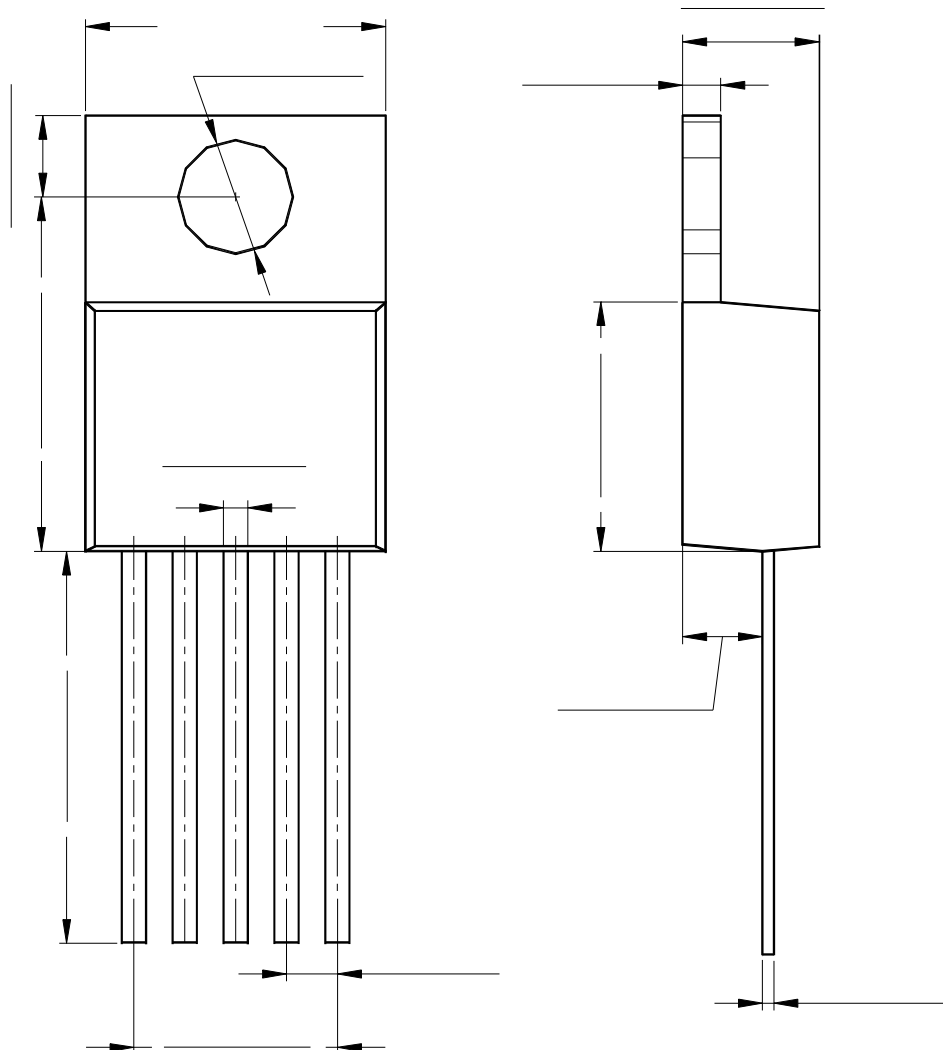
L1: Sumida CDRH127/LDNP-220MC or Equivalent

Figure 19. Typical Application of AP3003-12V



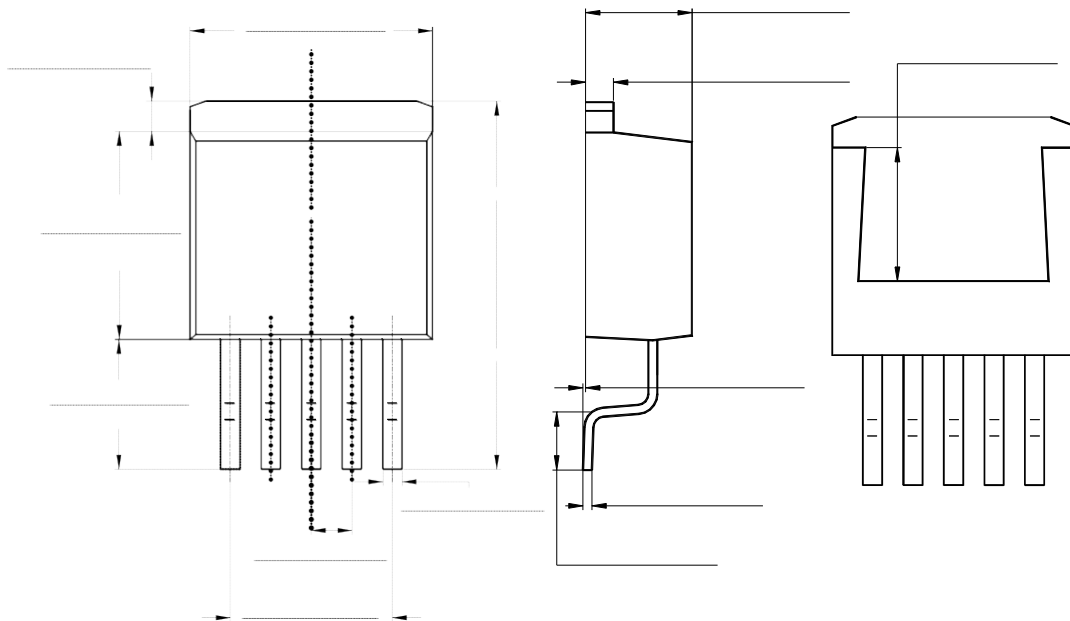
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Figure 20. Typical Application of AP3003-ADJ



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